



## RMA-223-AS, Rosin Mildly Active Solder Paste

### Product Data Sheet

#### Product Highlights

- ROM1 flux classification
- Exceptional print definition
- Excellent wetting on most board finishes
- Low voiding
- Long stencil life
- Wide process window
- REACH compliant
- Compatible with enclosed print heads
- Print & dispense grade solder paste available

#### Available Alloys

Alloy	Temp °C	Temp °F
63Sn/37Pb	183	361
62Sn/36Pb/2Ag	179	354
62.8Sn/36.8Pb/0.4Ag	179-183	354-361
60Sn/40Pb	183-191	361-376
43Sn/43Pb/14Bi	144-163	291-325
42Sn/58Bi	138	280
10Sn/88Pb/2Ag	268-290	514-554

#### Packaging

- 500 gram jars
- 700 gram cartridges
- 35 or 100 gram syringes
- ProFlow cassettes

#### Test Results

Test J-STD-004 or other requirements (as stated)	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No Corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	M: 0.5 – 2.0%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	M: <1 decade drop (Cleaned)
Surface Insulation Resistance 85 °C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	M: ≥100 MΩ (Cleaned)
Tack Value	IPC-TM-650: 2.4.44	48g
Viscosity - Malcom @ 10 RPM/25 °C (x10 <sup>3</sup> mPa/s)- Sn63/Pb37 T3/T4	IPC-TM-650: 2.4.34.4	Print: 185-255 Dispensing: 100-145
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

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## Printer Operation

The following are general guidelines for stencil printer optimization with RMA-223-AS. Some adjustments may be necessary based on your process requirements.

Print Speed: 25-100 mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

## Stencil Life

> 16 hours @ 30-45% RH and 20-25 °C

~ 6 hours @ 45-75% RH and 20-25 °C

## Cleaning

RMA-223-AS is a Rosin Mildly Active solder paste that can be left on the board for many SMT assemblies. For applications requiring cleaning, RMA-223-AS can be cleaned using flux residue removers such as Inventec Disper 607 and Disper 610.

## Recommended Profile

This profile is designed to serve as a starting point for process optimization using RMA-223-AS. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone, (140-180 °C) for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <60 seconds.

## Amtech Low Oxide Powder Distribution

Micron Size	Type	Pitch Requirements
45-75µ	Type-2	24 mil and above
25-45µ	Type-3	16-24 mil
20-38µ	Type-4	12-16 mil
15-25µ	Type-5	8-12 mil
5-15µ	Type-6	5-8 mil
2-11µ	Type-7	< 5 mil

Note: Type-6 and Type-7 may not be available in certain alloys. Other powder distributions are available on request.

## Storage

Solder paste should be stored between 3-8 °C (37-46 °F) to obtain the maximum refrigerated shelf life of six months. Unopened solder paste stored at room temperature, 25 °C (77 °F) will have a one month shelf life. Syringes and cartridges should be stored vertically in the refrigerator with the dispensing tip down. Allow 4-8 hours for solder paste to reach an operating temperature of 20-25 °C (68-77 °F). Keep the solder paste container sealed while warming the solder paste to operating temperature. **NEVER FREEZE SOLDER PASTE.**

